

Call for Papers/Exhibitors/Sponsors

IMAPS/ACerS 15th International Conference and Exhibition on Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT 2019)

April 17-19, 2019 Shanghai, China



General Chairs

Prof. Yongxiang Li
Shanghai Institute of Ceramics,
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Prof. Ji Zhou
School of Materials Science and
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Important dates

Abstract due: November 30, 2018

Notice of Acceptance: January 31, 2019

Deadline of full paper submission: April 17, 2019

Support by



Questions about CICMT 2019: cicmt2019@mail.sic.ac.cn or visit website

<http://www.imaps.org/ceramics/index.htm> or <http://cicmt2019.csp.escience.cn> (online soon)

Planned sessions and topics (include but not limited to)

1. Functional materials for passive/active devices and their properties

- Microwave/mm wave LTCC/ULTCC dielectric materials
- Ferroelectric/piezoelectric/pyroelectric/ferrite/multiferroic materials
- Sensitive ceramics/thermoelectric/electrocaloric materials
- Dielectric/ferroelectric/piezoelectric composites
- Pastes/inks/slurries for electronics

2. Material processing and device manufacturing technologies

- LTCC/HTCC and multilayer ceramic process
- Emerging low temperature sintering process
- Additive manufacturing /3D printing/ direct writing
- Advanced thick film processing
- Fine structuring technologies
- Emerging embedding/integration technologies

3. Devices for emerging technologies

- Circuits, antennas, and filters for MHz, GHz and THz for communications
- Automotive/aerospace/medical electronics/optoelectronics
- Flexible/wearable electronics
- Integrated physical/chemical/biological sensors and actuators
- Packaging and integration issues for MEMS and BioMEMS devices
- Batteries/fuel cells/ energy conversion systems
- Micro-reactors/micro-fluidic devices

4. Design, modeling, simulation, characterization and reliability

- Metamaterials design, realization and characterization
- High frequency devices design/modeling/simulation
- Materials and devices characterization
- Material and device reliability, lifetime, and failure estimation
- Thermal management/thermal transfer simulation

Conference publications

The participants are invited to submit full papers to the *International Journal of Applied Ceramics Technology* (for the materials-focused papers) or *IMAPS Journal of microelectronics and electronic packaging* (for the packaging-focused papers).

Exhibition

The suppliers of LTCC processing, microelectronic assembly and packaging, 3D printing, electric/magnetic/structural characterization facilities are invited to take part in the Exhibition.

Sponsorship

Companies are invited to sponsor the naming banquet and student poster award. The sponsors would have a series of priorities except for the same right of exhibitors.